

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
31 March 2005 (31.03.2005)

PCT

(10) International Publication Number  
**WO 2005/029578 A1**

(51) International Patent Classification<sup>7</sup>: **H01L 21/768**

(21) International Application Number:  
PCT/IB2004/051676

(22) International Filing Date:  
2 September 2004 (02.09.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
03103525.6 24 September 2003 (24.09.2003) EP

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

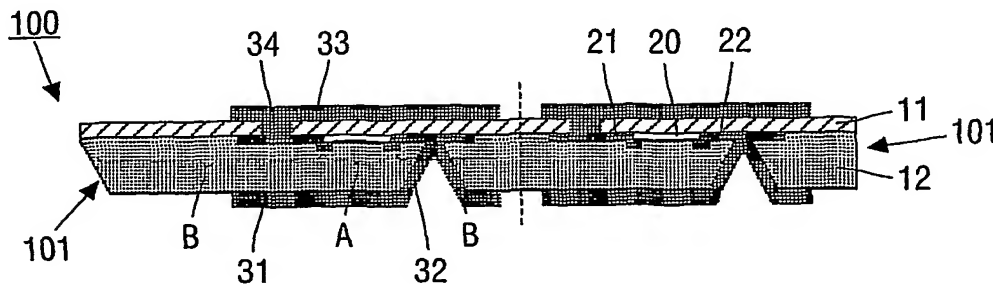
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING SAME, IDENTIFICATION LABEL AND INFORMATION CARRIER



(57) Abstract: The semiconductor device (100) comprises an integrated circuit (20) and a first and a second contact face (31,33). These are connected with vertical interconnects (32,34) to the integrated circuit (20). This integrated circuit (20) is present in a semiconductor layer of a substrate. This substrate is absent in a non-active area (B). This leads to the fact that on the side faces (101) of the device (100) neither conductive material nor parts of the semiconductor substrate are exposed. On lamination of the device between two metallized foils into an identification label, the risk of short-circuitry due to undesired contact at the side face (101) of the device (100), is prevented thereby.